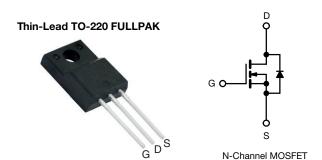


E Series Power MOSFET



PRODUCT SUMMA	RY		
V _{DS} (V) at T _J max.	650)	
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V 0.269		
Q _g max. (nC)	64		
Q _{gs} (nC)	_{as} (nC) 8		
Q _{gd} (nC)	13		
Configuration	Sing	le	

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
- Fluorescent ballast lighting
- Industrial
 - Welding
- Induction heating
- Motor drives
- Battery chargers
- Renewable energy
- Solar (PV inverters)

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA14N60E-E3
Lead (Pb)-free and halogen-free	SiHA14N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	600	V	
Gate-source voltage			V_{GS}	± 30	0	
Continuous drain current (T,j = 150 °C) e	V _{GS} at 10 V	T _C = 25 °C		13		
Continuous drain current (1) = 150 C)	VGS at 10 V	T _C = 100 °C	I _D	8	Α	
Pulsed drain current ^a			I _{DM}	32		
Linear derating factor				1.2	W/°C	
Single pulse avalanche energy b	gle pulse avalanche energy ^b E _{AS} 136		mJ			
Maximum power dissipation			W			
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150	°C			
Drain-source voltage slope	T _J = 125 °C		dV/dt 70		\//	
Reverse diode dV/dt ^d			αν/αι	32	- V/ns	
Soldering recommendations (peak temperature) c	for	10 s		300	°C	
Mounting torque	M3 s	screw		0.6	Nm	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 3.1 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$
- e. Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	3.8	C/VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				•	•	l .	
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.73	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zana mata walta sa dhaila annina		V _{DS} =	= 600 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 7 A	-	0.269	0.309	Ω
Forward transconductance	9 _{fs}	V _{DS}	s = 30 V, I _D = 7 A	-	3.8	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 1 \text{ MHz}$		-	1205	-	pF
Output capacitance	C _{oss}			-	62	-	
Reverse transfer capacitance	C _{rss}			-	5	-	
Effective output capacitance, energy related ^a	$C_{o(er)}$	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	52	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	177	-	
Total gate charge	Qg			-	32	64	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 7 A, V_{DS} = 480 V$	-	8	-	nC
Gate-drain charge	Q _{gd}			_	13	-	
Turn-on delay time	t _{d(on)}			-	15	30	
Rise time	t _r	$V_{DD} = 480 \text{ V}, I_D = 7 \text{ A},$		-	19	38	
Turn-off delay time	t _{d(off)}	V _{GS} =	= 10 V, $R_q = 9.1 \Omega$	_	35	70	ns
Fall time	t _f				15	30	
Gate input resistance	R_g	f = 1 MHz, open drain		0.38	0.75	1.5	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	13	
Pulsed diode forward current	I _{SM}			-	-	32	_ A
Diode forward voltage	V _{SD}	T _J = 25 °	C, I _S = 7 A, V _{GS} = 0 V	-	-	1.2	V
Reverse recovery time	t _{rr}			-	281	-	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 7 \text{ A},$ $dI/dt = 100 \text{ A/µs}, V_R = 25 \text{ V}$		-	3.4	-	μC
Reverse recovery current	I _{RRM}			_	22	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

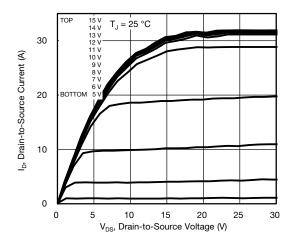


Fig. 1 - Typical Output Characteristics

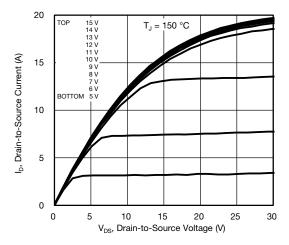


Fig. 2 - Typical Output Characteristics

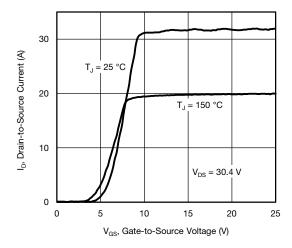


Fig. 3 - Typical Transfer Characteristics

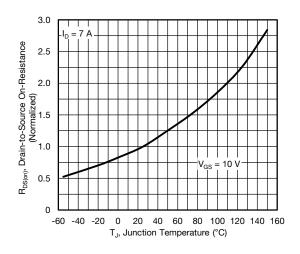


Fig. 4 - Normalized On-Resistance vs. Temperature

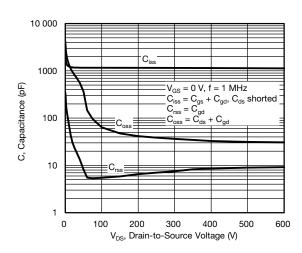


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

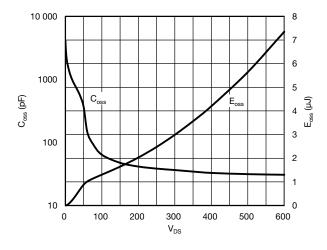


Fig. 6 - Coss and Eoss vs. VDS



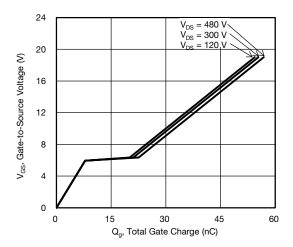


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

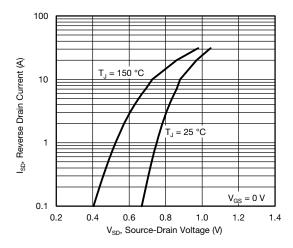


Fig. 8 - Typical Source-Drain Diode Forward Voltage

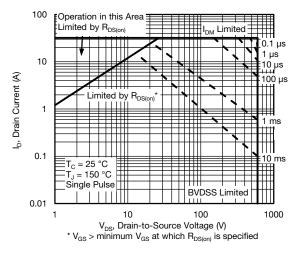


Fig. 9 - Maximum Safe Operating Area

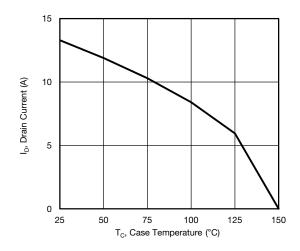


Fig. 10 - Maximum Drain Current vs. Case Temperature

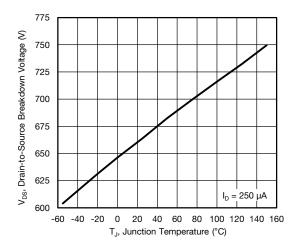


Fig. 11 - Temperature vs. Drain-to-Source Voltage



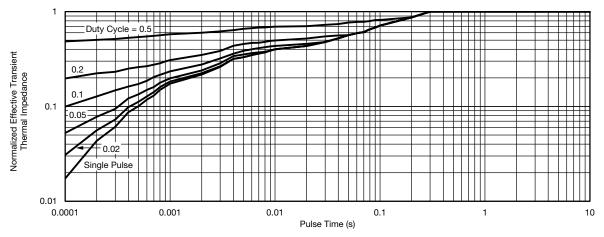


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

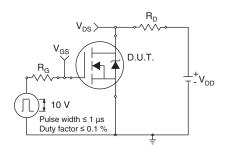


Fig. 13 - Switching Time Test Circuit

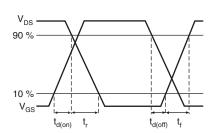


Fig. 14 - Switching Time Waveforms

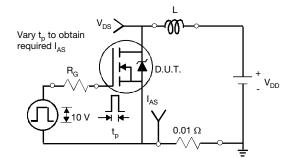


Fig. 15 - Unclamped Inductive Test Circuit

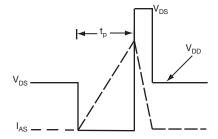


Fig. 16 - Unclamped Inductive Waveforms

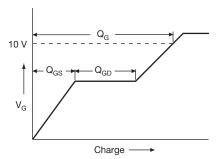


Fig. 17 - Basic Gate Charge Waveform

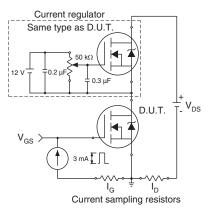
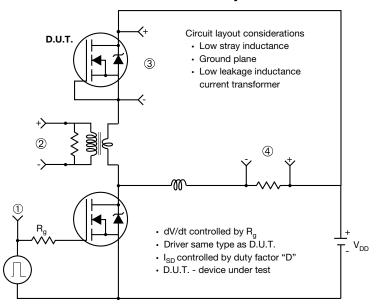


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



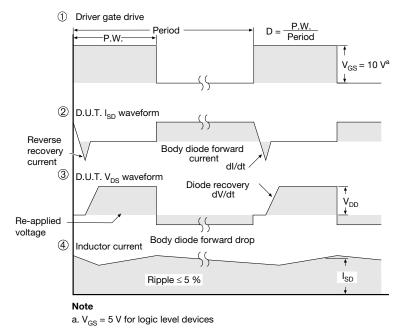
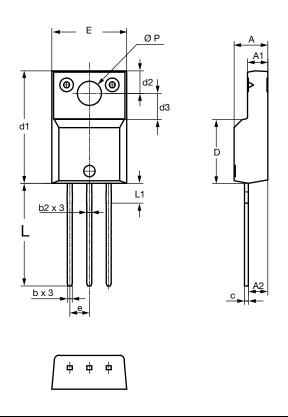


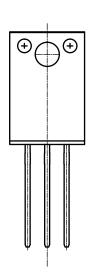
Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead





SYMBOL		DIMEN	ISIONS		
	MILLIN	IETERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	4.30	4.70	0.169	0.185	
A1	2.50	2.90	0.098	0.114	
A2	2.40	2.80	0.094	0.110	
b	0.60	0.80	0.024	0.031	
b2	0.60	0.90	0.024	0.035	
С	-	0.60	-	0.024	
D	8.30	8.70	0.327	0.342	
d1	14.70	15.30	0.579	0.602	
d2	2.90	3.10	0.114	0.122	
d3	3.30	3.70	0.130	0.146	
Е	9.70	10.30	0.382	0.406	
е	2.50	2.70	0.098	0.106	
L	13.40	13.80	0.528	0.543	
L1	1.00	2.80	0.039	0.110	
ØP	3.00	3.40	0.118	0.134	

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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Vishay

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